查询DS2102SY供应商





Rectifier Diode

DS4171-5.1 December 2001

Replaces September 2001 version, DS4171-5.0

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- Rectification
- Freewheel Diode
- DC Motor Control
- Power Supplies
- Welding
- Battery Chargers

VOLTAGE RATINGS

Type Number	Repetitive Peak Reverse Voltage V _{RRM} V	Conditions
DS2102SY20	2000	$V_{RSM} = V_{RRM} + 100V$
DS2102SY19	1900	
DS2102SY18	1800	
DS2102SY17	1700	
DS2102SY16	1600	
DS2102SY15	1500	



ORDERING INFORMATION

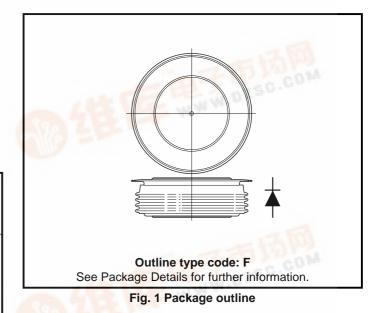
When ordering, select the required part number shown in the Voltage Ratings selection table, e.g.:

DS2102SY18

Note: Please use the complete part number when ordering and quote this number in any future correspondance relating to your order.

KEY PARAMETERS

- V_{RRM} 2000V
- I_{F(AV)} 6654A
- I_{FSM} 100000A







CURRENT RATINGS

T_{case} = 75°C unless otherwise stated

Symbol	Parameter	Conditions	Max.	Units			
Double Sid	Double Side Cooled						
I _{F(AV)}	Mean forward current	Half wave resistive load	6654	А			
I _{F(RMS)}	RMS value	-	10452	А			
I _F	Continuous (direct) forward current	-	9275	А			
Single Side Cooled (Anode side)							
l _{F(AV)}	Mean forward current	Half wave resistive load	4227	А			
I _{F(RMS)}	RMS value	-	6640	А			
I _F	Continuous (direct) forward current	-	5403	А			

T_{case} = 100°C unless otherwise stated

Symbol	Parameter	Conditions		Units		
Double Side Cooled						
I _{F(AV)}	Mean forward current	Half wave resistive load, $T_{case} = 100^{\circ}C$	5460	А		
I _{F(RMS)}	RMS value	$T_{case} = 100^{\circ}C$	8575	А		
I _F	Continuous (direct) forward current	$T_{case} = 100^{\circ}C$	7450	А		
Single Side Cooled (Anode side)						
I _{F(AV)}	Mean forward current	Half wave resistive load, T _{case} = 100°C	3410	А		
I _{F(RMS)}	RMS value	T _{case} = 100°C	5356	А		
l _F	Continuous (direct) forward current	T _{case} = 100°C	4260	А		



SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
I _{FSM}	Surge (non-repetitive) forward current	10ms half sine; T _{case} = 175°C	80.0	kA
l ² t	I ² t for fusing	V _R = 50% V _{RRM} - 1/4 sine	32 x 10 ⁶	A²s
I _{FSM}	Surge (non-repetitive) forward current	10ms half sine; T _{case} =175°C	100.0	kA
l²t	I ² t for fusing	V _R = 0	50 x 10 ⁶	A ² s

THERMAL AND MECHANICAL DATA

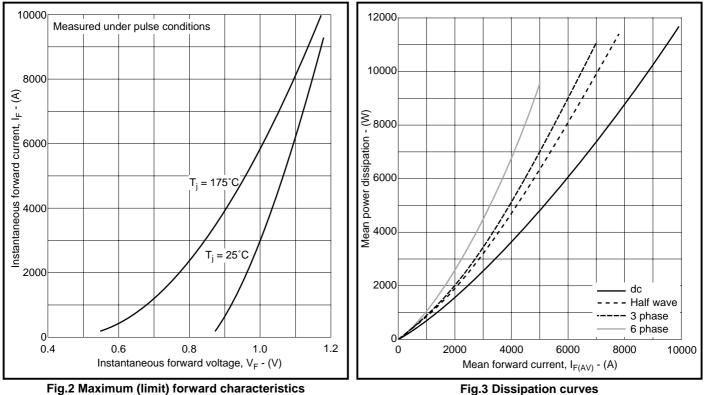
Symbol	Parameter	Conditions		Min.	Max.	Units
R _{th(j-c)}	Thermal resistance - junction to case	Double side cooled	dc	-	0.0095	°C/W
			Anode dc	-	0.019	°C/W
		Single side cooled	Cathode dc	-	0.019	°C/W
D	Thermal resistance - case to heatsink	Clamping force 43.0kN with mounting compound	Double side	-	0.002	°C/W
R _{th(c-h)}			Single side	-	0.004	°C/W
т	Virtual junction temperature	Forward (conducting)		-	200	°C
T_{vj}		Reverse (blocking)		-	175	°C
T _{stg}	Storage temperature range			-55	175	°C
-	Clamping force			38.0	47.0	kN



CHARACTERISTICS

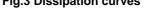
Symbol	Parameter	Conditions	Min.	Max.	Units
V _{FM}	Forward voltage	At 3000A peak, T _{case} = 25°C	-	1.0	V
I _{RM}	Peak reverse current	At V_{RRM} , $T_{case} = 175^{\circ}C$	-	100	mA
Q _s	Total stored charge	$I_{F} = 2000A, dI_{RR}/dt = 3A/\mu s$ $T_{case} = 175^{\circ}C, V_{R} = 100V$	-	2600	μC
I _{rr}	Peak reverse recovery current		-	120	Α
V _{to}	Threshold voltage	At $T_{vj} = 175^{\circ}C$	-	0.75	V
r _T	Slope resistance	At $T_{vj} = 175^{\circ}C$	-	0.0415	mΩ

CURVES



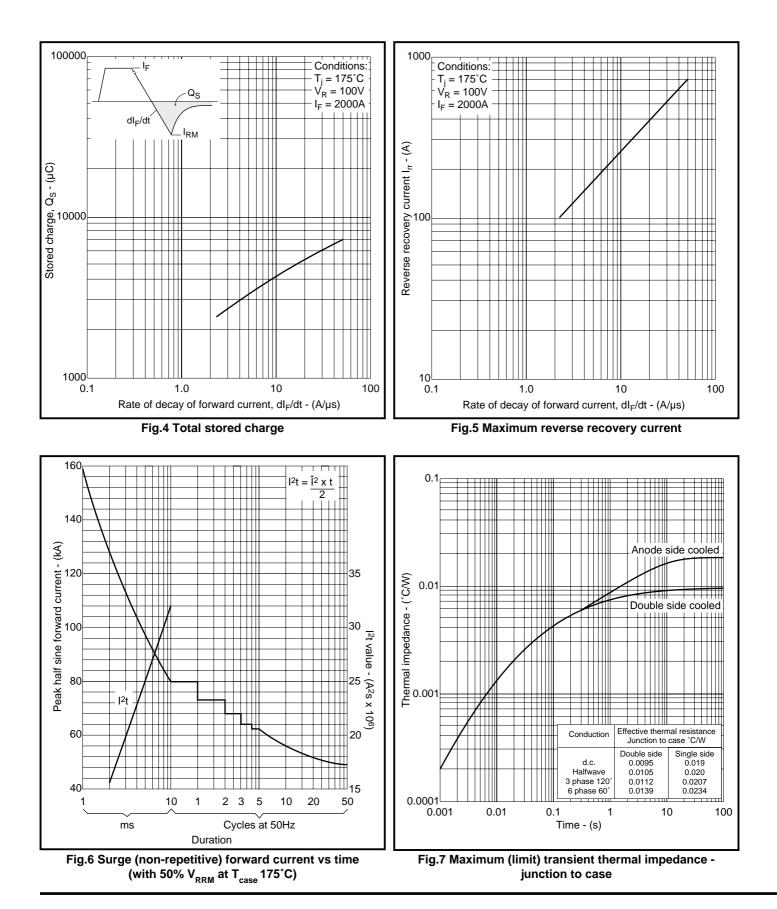
V_{FM} Equation:-

 $V_{FM} = A + Bln (I_F) + C.I_F + D.\sqrt{I_F}$



Where A = 0.402091B = 0.011718 $C = 6.48 \times 10^{-5}$ D = 0.005977these values are valid for $T_j = 125^{\circ}C$ for $I_F 500A$ to 10000A

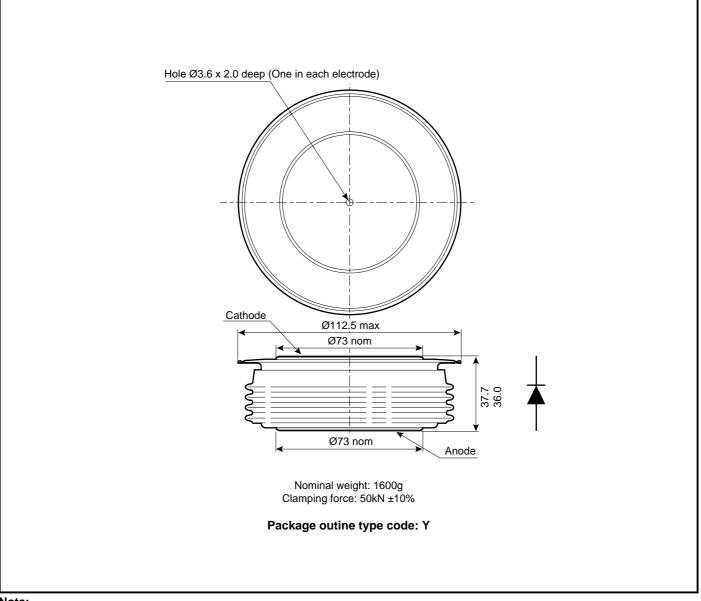






PACKAGE DETAILS

For further package information, please contact your nearest Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Note:

1. Package maybe supplied with pins and/or tags.



POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group continues to offer high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the up to date CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete solution (PACs).

DEVICE CLAMPS

Disc devices require the correct clamping force to ensure their safe operation. The PACs range offers a varied selection of pre-loaded clamps to suit all of our manufactured devices. This include cube clamps for single side cooling of 'T' 22mm

Clamps are available for single or double side cooling, with high insulation versions for high voltage assemblies.

Please refer to our application note on device clamping, AN4839

HEATSINKS

Power Assembly has its own proprietary range of extruded aluminium heatsinks. They have been designed to optimise the performance or our semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest Sales Representative or Customer Services.



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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

No Annotation: The product parameters are fixed and the product is available to datasheet specification.

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